



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-10-12
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD3NK80Z-1	CLIK*E282B62	A	SHENZHEN B/E	2015-10-12
Amount		UoM	Unit type	ST ECOPACK Grade
310.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DIP	6.1, 6.5, 2.3	3	THROUGH HOLE	
Comment	IPAK TO-251			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	CLIK*E282B62					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.800	mg	supplier	die	Silicon (Si)	7440-21-3		5.598	mg	965172	18058
				supplier	metallization	Aluminium (Al)	7429-90-5		0.079	mg	13621	255
				supplier	Passivation	Silicon Nitride	12033-89-5		0.026	mg	4483	84
				supplier	Passivation	Silicon Oxide	7631-86-9		0.042	mg	7241	135
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	517	10
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.038	mg	6552	123
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.014	mg	2414	45
Leadframe	Copper & its alloys	184.074	mg	supplier	alloy	Copper (Cu)	7440-50-8		181.496	mg	985995	585471
				supplier	alloy	Iron (Fe)	7439-89-6		0.182	mg	989	587
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.055	mg	299	177
				supplier	metallization	Nickel (Ni)	7440-02-0		2.341	mg	12718	7552
				supplier	metallization	Nickel (Ni)	7440-02-0		2.341	mg	12718	7552
Soft solder	Solder	5.432	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	5.187	mg	954897	16732
				supplier	solder	Silver (Ag)	7440-22-4		0.136	mg	25037	439
				supplier	solder	Tin (Sn)	7440-31-5		0.109	mg	20066	352
Bonding wires	Other inorganic materials	0.116	mg	supplier	wire	Copper (Cu)	7440-50-8		0.116	mg	1000000	374
Encapsulation	Other Organic Materials	110.875	mg	supplier	mold compound	Silica, vitreous	60676-86-0		97.016	mg	875003	312955
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-b	EC 413-900-7		4.435	mg	40000	14306
				supplier	mold compound	Epoxy Resin	25068-38-6		3.326	mg	29998	10729
				supplier	mold compound	phenol resin	29690-82-2		5.544	mg	50002	17884
				supplier	mold compound	Carbon black	1333-86-4		0.554	mg	4997	1787
Connections coating	Solder	3.703	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.703	mg	1000000	11945